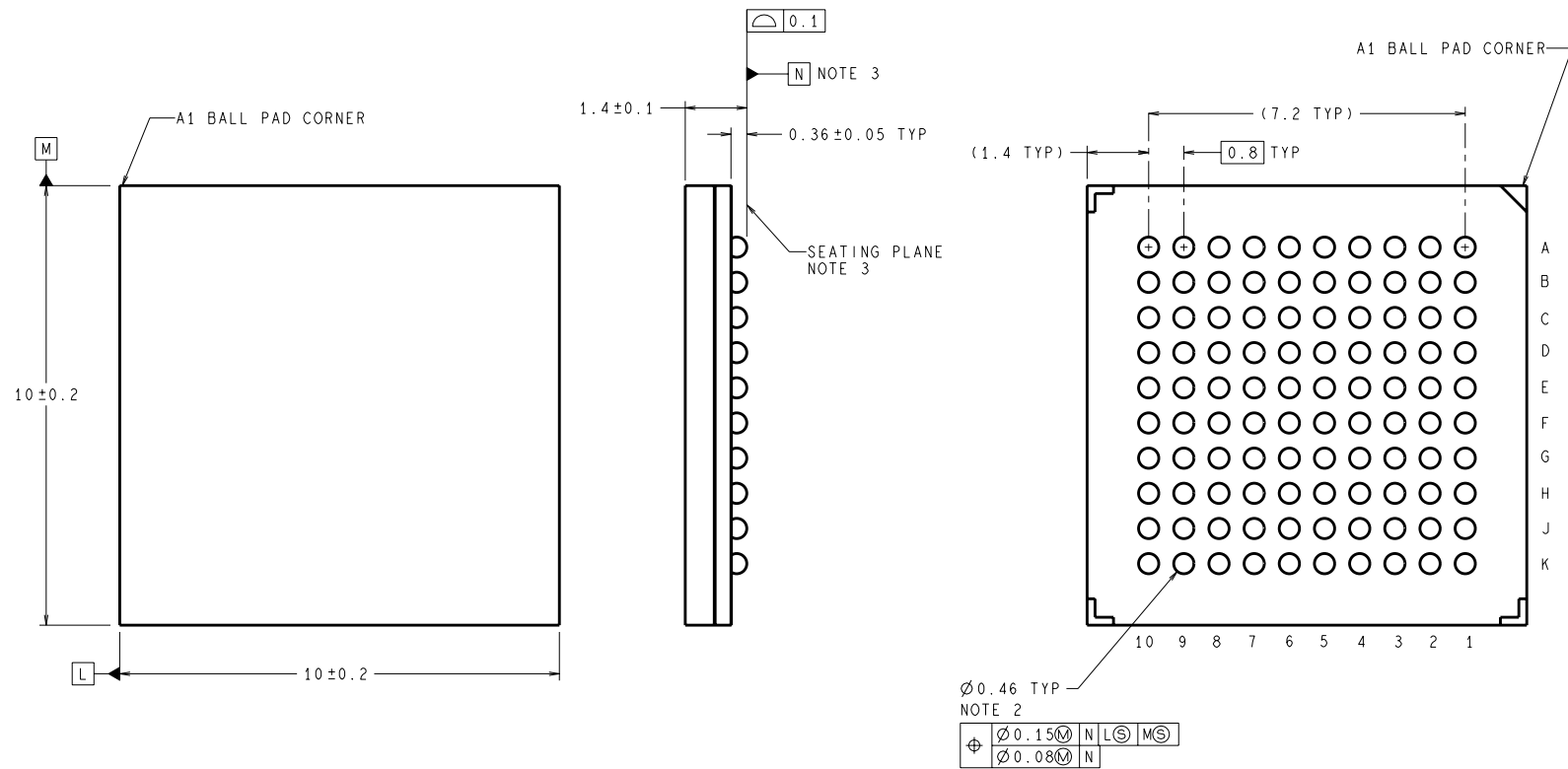


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12030	06/23/1998	TL/AP
B	REVISE TITLE	12173	03/18/1999	MS/



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
2. DIMENSION MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
3. PRIMARY DATUM N AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. NO JEDEC REGISTRATION AS OF JUNE 1998.

Ø 0.46 TYP  
NOTE 2

⊕	Ø 0.15	N	L	MS
	Ø 0.08	N		

APPROVALS	DATE	National Semiconductor		
DRAWN T. LEQUANG	06/23/1998	2900 Semiconductor dr., Santa Clara, CA 95052-8090		
DFTG. CHK.		FBGA, PLASTIC, LAMINATED, 0.8mm PITCH, 10 X 10 X 1.4mm, 100 BALL		
ENGR. CHK.		SCALE	SIZE	DRAWING NUMBER
		N/A	C	(SC)MKT-SLC100A
		REV	REV	
		DO NOT SCALE DRAWING		SHEET 1 of 1